

Qualification Results Summary for Automotive Grade 1 Dual-Die in LQFP_EP at UT3

QUALIFICATION RESULTS			
TEST	SPECIFICATION	SAMPLE SIZE	RESULT
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	PASS
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 77	PASS
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC <i>JESD22-A118</i>	3 x 77	PASS
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	3 x 77	PASS
High Temperature Operating Life (HTOL)	JEDEC <i>JESD22-A108</i>	3 x 77	PASS
Latch-Up	JEDEC <i>JESD78</i>	6/level	PASS ±200mA
Electrostatic Discharge <i>Human Body Model</i>	ESDA/JEDEC <i>JS-001</i>	3/voltage	PASS ±1000V
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	JEDEC <i>JS-002</i>	3/voltage	PASS ±750V

* These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: 1. Bake – 24 hours at 125°C; 2. Soak – unbiased soak for 192 hours at 30°C, 60%RH; 3. Reflow – three passes through a reflow oven with a peak temperature of 260°C. TC samples were subjected to wire-pull test after 500 cycles within specification limits.